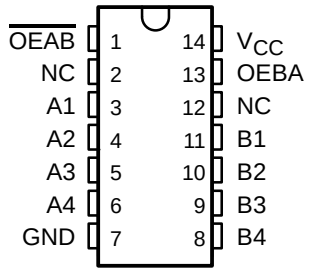
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) Submicron Process**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Typical V_{OHV} (Output V_{OH} Undershoot) > 2 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages**

D, DB, OR PW PACKAGE
(TOP VIEW)



description

This quadruple bus transceiver is designed for 2.7-V to 3.6-V V_{CC} operation.

The SN74LVC243 is designed for asynchronous communications between data buses. The control-function implementation allows for maximum flexibility in timing. The device allows data transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic levels at the output-enable (OEBA and $\overline{\text{OEAB}}$) inputs. The output-enable inputs can be used to disable the device so that the buses are effectively isolated.

The dual-enable configuration gives the quadruple bus transceivers the capability to store data by simultaneous enabling of OEBA and $\overline{\text{OEAB}}$. Each output reinforces its input in this transceiver configuration. Thus, when both control inputs are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (eight in all) remain at their states. The 4-bit codes appearing on the two sets of buses will be identical for the SN74LVC243.

The SN74LVC243 is characterized for operation from –40°C to 85°C.

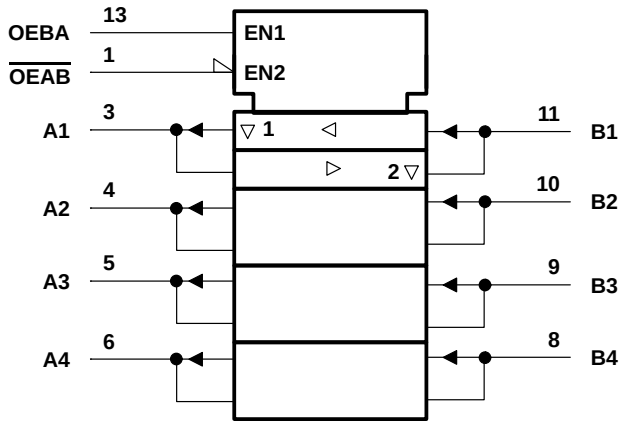
FUNCTION TABLE

INPUTS		FUNCTION
$\overline{\text{OEAB}}$	OEBA	
L	L	A to B
H	H	B to A
H	L	Isolation
L	H	Latch A and B (A = B)

PRODUCT PREVIEW

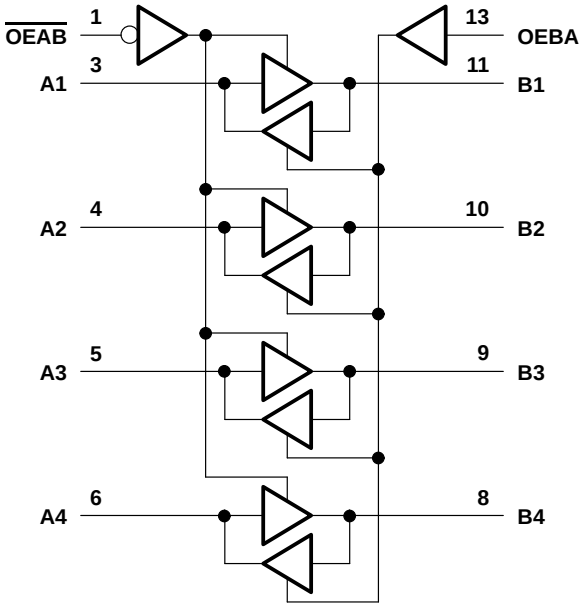
EPIC is a trademark of Texas Instruments Incorporated.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



PRODUCT PREVIEW

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 4.6 V
Input voltage range, V_I (except I/O ports) . . . . . –0.5 V to 4.6 V
Input voltage range, V_I (I/O ports) (see Note 1) . . . . . –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) . . . . . –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0) . . . . . –50 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) . . . . . ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) . . . . . ±50 mA
Continuous current through V_{CC} or GND . . . . . ±100 mA
Maximum power dissipation at T_A = 55°C (in still air): D package . . . . . 1.25 W
DB package . . . . . 0.5 W
PW package . . . . . 0.5 W
Storage temperature range . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: This value is limited to 4.6 V maximum.

recommended operating conditions (see Note 2)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2.7	3.6	V
V_{IH}	High-level input voltage	V_{CC} = 2.7 V to 3.6 V	2		V
V_{IL}	Low-level input voltage	V_{CC} = 2.7 V to 3.6 V		0.8	V
V_I	Input voltage		0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 2.7 V		–12	mA
		V_{CC} = 3 V		–24	
I_{OL}	Low-level output current	V_{CC} = 2.7 V		12	mA
		V_{CC} = 3 V		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	10	ns/V
T_A	Operating free-air temperature		–40	85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

PRODUCT PREVIEW

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V_{CC}†	T_A = –40°C to 85°C			UNIT
					MIN	TYP	MAX	
V_{OH}		I_{OH} = –100 μA		MIN to MAX	V_{CC}–0.2			V
		I_{OH} = – 12 mA		2.7 V	2.2			
				3 V	2.4			
		I_{OH} = – 24 mA		3 V	2			
V_{OL}		I_{OL} = 100 μA		MIN to MAX			0.2	V
		I_{OL} = 12 mA		2.7 V			0.4	
		I_{OL} = 24 mA		3 V			0.55	
I_I		V_I = V_{CC} or GND		3.6 V			±5	μA
I_{OZ}‡		V_O = V_{CC} or GND		3.6 V			±10	μA
I_{CC}		V_I = V_{CC} or GND,	I_O = 0	3.6 V			20	μA
ΔI_{CC}		V_{CC} = 3 V to 3.6 V, Other inputs at V_{CC} or GND	One input at V_{CC} – 0.6 V,				500	μA
C_i	Control inputs	V_I = V_{CC} or GND		3.3 V				pF
C_{io}	A or B ports	V_O = V_{CC} or GND		3.3 V				pF

† For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

PRODUCT PREVIEW

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